Smart Inserter 20
SI20

An affordable solution to facilitate small volumes of Biometric, Contact & Dual interface Cards production

Validate your embedding process with the SI20

The **SI20** is a simple, compact and affordable system allowing performing various embedding tests on cards in a view developing an embedding process before implementing it into a bigger system like the SI700. For new card projects where:

o specific or new components need to be embedded on cards in ISO or non-ISO positions - like a fingerprint sensor or a smart object,
o particular card material needs to be used - like metal,
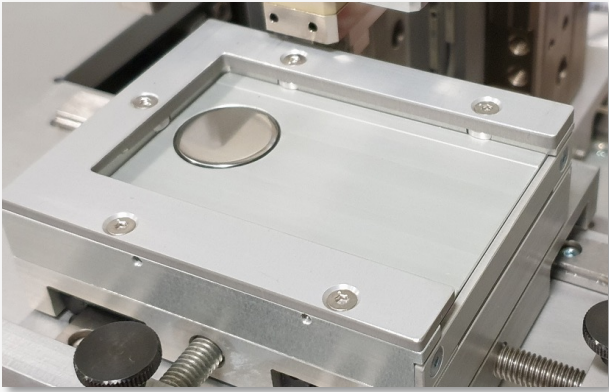o a new adhesive or conductive glue need to be used,

The **SI20** is the perfect system to exercise these new elements and technologies on a small quantity of cards before launching a larger production.
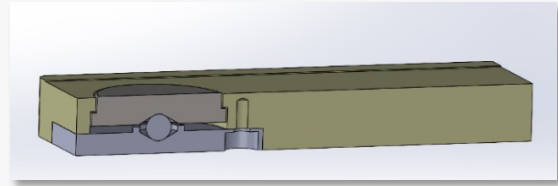
The SI20 is made in France

Smart Inserter 20 Specifications

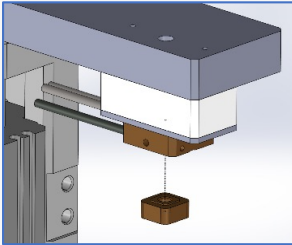|	
System Functionality	Press a chip module, a contact plate, a biometric sensor or eventually a smart object in any position on the card surface except 1mm from the right and left edge of the card, and 2mm from the top and bottom of the card
Preliminary conditions	- A cavity should be milled on the card, depending on the chip or sensor specification - The chip/contact plate/sensor film should be laminated with glue
Embedding placement	Placement is done manually
Connecting technologies to the card inlay	2 supported technologies allow connecting the chip, contact plate or sensor to the contact pads of the card inlay: - ACF glue (Anisotropic adhesive conductive glue) - Edgelink® from Linxens
Presser heads temperature, pressure force, pressure time	- From ambiant to 250°C - Pressure force up to 6 bars - Pressure time up to 20 sec
Card Types Supported	ISO/IEC 7810 ID-1 Size; 30 mil (±10%)
Card Materials Supported	Polycarbonate, composite, PVC, ABS, metal
System dimensions	H 336 mm x W 396 mm x L 450 mm
Module weight	15 kg
Power supply / Compressed air supply	120V / 240V, 50 or 60 Hz / Compressed air: 6 bars, 8 liters/minute

Smart Inserter 20 Key Features

Flatness compensation

A ball joint anvil system implemented on the card support ensures flatness at the chip or sensor position during pressing.

Fast head replacement

Pressing head format (sensors, EMV module..) replacement is easy and fast due to a unique screw.

Accurate pressing value

Air pressure is precisely controlled and displayed (in bars) for each head. There is one controller per head.

Easy use tactile screen

The operating touch screen allows easily setting up all embedding parameters including temperature, pressure time, number of pressings per head.

Once an embedding process is defined and tested, it can be saved or modified in the SI20 internal memory (up to 50 process).

About Smart Technology Services (STS)

STS provides high level support services and card production & personalization solutions to card manufacturers and bureaus.

The company provides service support activities for card central issuance systems, and second hand systems. It also supplies the SE30 & SE1000, desktop card personalization systems, and the SI20, SM20, SPu20 and SI700, versatile card production systems for dual interface and biometric cards.